

(0.80 mm) .0315" X (1.80 mm) .071"

EXTREME DENSITY & PERFORMANCE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?NVAM-C

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Shield:

Copper Alloy

Plating:

Au or Sn over

50 μm (1.27 μm) Ni

Current Rating:

Testing Now!

RoHS Compliant:

Yes

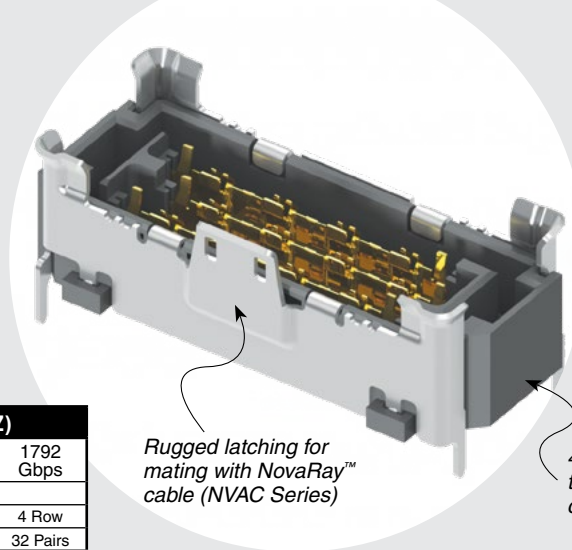
Lead-Free Solderable:

Yes

Mates with:

NVAC

NRZ	PAM4
56	112
Gbps	Gbps



Up to 4.0 Tbps aggregate data rate

Rugged latching for mating with NovaRay™ cable (NVAC Series)

40 percent smaller than conventional cable connectors

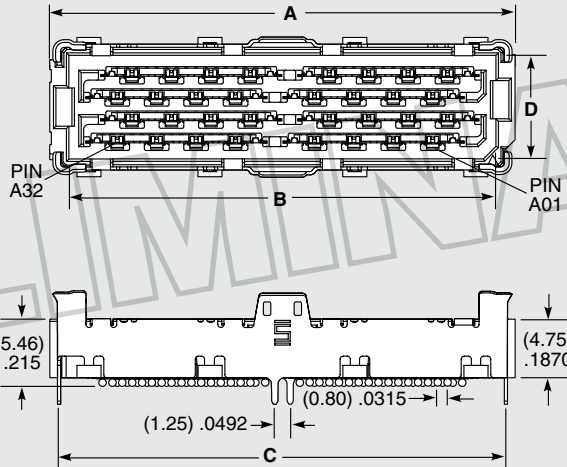
AGGREGATE DATA RATE (NRZ)

448 Gbps	672 Gbps	896 Gbps	1344 Gbps	1792 Gbps
1 Bank		2 Bank		
2 Row	3 Row	4 Row	2 Row	3 Row
8 Pairs	12 Pairs	16 Pairs	24 Pairs	32 Pairs

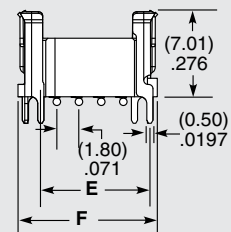
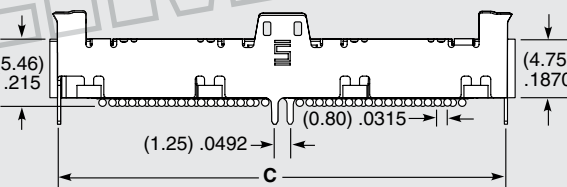
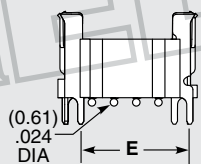
NVAM	STYLE	NO. OF ROWS	NO. OF BANKS	02.0	PLATING OPTION	SOLDER TYPE	C
	-DP = 4 pairs per wafer	-02 = 2 Rows -03 = 3 Rows -04 = 4 Rows	-1 = 1 Bank -2 = 2 Banks		-S = 30 μm (0.76 μm) Gold on contact area, Matte Tin on solder tail	-2 = Lead-Free Solder Charge	

NO. OF BANKS	A	B	C
-1	(21.75) .856	(18.65) .734	(20.25) .797
-2	(37.75) 1.486	(34.65) 1.364	(36.25) 1.427

NO. OF ROWS	D	E	F
-02	(4.80) .189	(5.25) .207	(7.70) .303
-03	(6.60) .260	(7.05) .278	(9.50) .374
-04	(8.40) .331	(8.85) .348	(11.30) .445



NVAM-DP-04-2-02.0-X-X-C SHOWN



Note:
Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.